



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Morrison, et al.

Docket No.: TI-31373

Serial No.: 10/034,827

Examiner: Mitchell, J. M.

Filed: 01/03/02

Art Unit: 2827

For: Chip-scale Packages Stacked on Folded Interconnector for Vertical
Assembly on Substrates

Amendment under 37 CFR 1.111

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the
U.S. Postal Service as First Class Mail in an envelope addressed to:
Assistant Commissioner for Patents, Washington, D.C. 20231 on

2-21-03

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 10/23/02. They are respectfully submitted as a full and complete response to that Action. A petition for a one-month extension of time accompanies this paper. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

Please amend the application as follows:

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TECHNOLOGY CENTER 2800